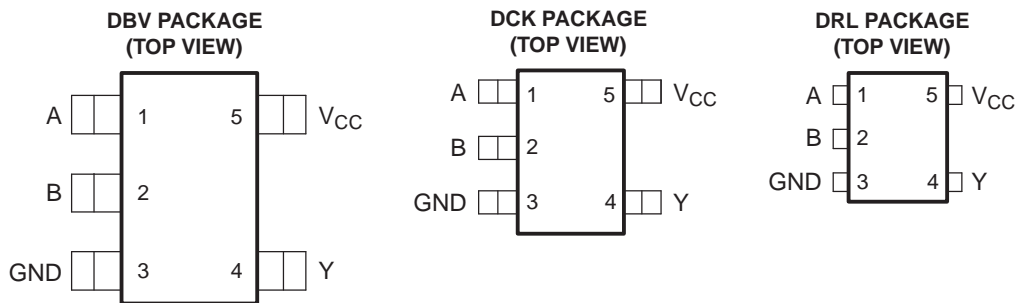


## FEATURES

- **Controlled Baseline**
    - One Assembly Site
    - One Test Site
    - One Fabrication Site
  - **Extended Temperature Performance of –55°C to 125°C**
  - **Enhanced Diminishing Manufacturing Sources (DMS) Support**
  - **Enhanced Product-Change Notification**
  - **Qualification Pedigree** <sup>(1)</sup>
    - **Operating Range of 2 V to 5.5 V**
    - **Max  $t_{pd}$  of 8.5 ns at 5 V**
    - **Low Power Consumption, 10  $\mu$ A Max  $I_{CC}$**
    - **$\pm$ 8 mA Output Drive at 5 V**
    - **Schmitt Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time**
    - **ESD Protection Exceeds JESD 22**
      - 2000-V Human-Body Model (A114-A)
      - 200-V Machine Model (A115-A)
      - 1000-V Charged-Device Model (C101)
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



See mechanical drawings for dimensions.

## DESCRIPTION/ORDERING INFORMATION

This device contains a single 2-input NOR gate that performs the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = \overline{A + B}$  in positive logic.

### ORDERING INFORMATION<sup>(1)</sup>

T <sub>A</sub>	PACKAGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOT (SC-70) - DCK Reel of 3000	SN74AHC1G02MDCKREP	CGC

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).  
 (2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN74AHC1G02-EP SINGLE 2-INPUT POSITIVE-NOR GATE

SCLS708—FEBRUARY 2008

**FUNCTION TABLE**

INPUTS		OUTPUT Y
A	B	
H	X	L
X	H	L
L	L	H

**LOGIC DIAGRAM (POSITIVE LOGIC)**



## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	7	V
$V_O$	Output voltage range <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		-20 mA
$I_{OK}$	Output clamp current	$V_O < 0$ or $V_O = 0$ to $V_{CC}$		$\pm 20$ mA
$I_O$	Continuous output current	$V_O = 0$ to $V_{CC}$		$\pm 25$ mA
	Continuous current through $V_{CC}$ or GND	$V_{CC}$ or GND		$\pm 50$ mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	DCK package		252 °C/W
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

**Recommended Operating Conditions<sup>(1)</sup>**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2\text{ V}$	1.5	V
		$V_{CC} = 3\text{ V}$	2.1	
		$V_{CC} = 5.5\text{ V}$	3.85	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2\text{ V}$	0.5	V
		$V_{CC} = 3\text{ V}$	0.9	
		$V_{CC} = 5.5\text{ V}$	1.65	
$V_I$	Input voltage	0	5.5	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-Level output current	$V_{CC} = 2\text{ V}$	-50	$\mu\text{A}$
		$V_{CC} = 3.3\text{ V} \pm 0.3$	-4	mA
		$V_{CC} = 5\text{ V} \pm 0.5$	-8	
$I_{OL}$	Low-Level output current	$V_{CC} = 2\text{ V}$	50	$\mu\text{A}$
		$V_{CC} = 3.3\text{ V} \pm 0.3$	4	mA
		$V_{CC} = 5\text{ V} \pm 0.5$	8	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$	100	ns/V
		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$	20	
$T_A$	Operating free-air temperature	-55	125	$^{\circ}\text{C}$

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**Electrical Characteristics**

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V	1.9	2		1.9	V	
		3 V	2.9	3		2.9		
		4.5 V	4.4	4.5		4.4		
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V				0.1	V	
		3 V				0.1		
		4.5 V				0.1		
	I <sub>OL</sub> = 4 mA	3 V			0.36	0.44		
	I <sub>OL</sub> = 8 mA	4.5 V			0.36	0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1	±1	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, O = 0	5.5 V			1	10	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		4	10	10	pF	

**Switching Characteristics**

over operating free-air temperature range, V<sub>CC</sub> = 3.3 ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF		8.1	11.4	1	13	ns
t <sub>PHL</sub>					8.1	11.4	1	13	

**Switching Characteristics**

over operating free-air temperature range, V<sub>CC</sub> = 5 ± 0.5 V (unless otherwise noted) (see Figure 1)

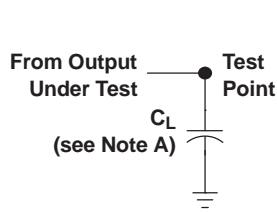
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	C <sub>L</sub> = 50 pF		5.1	7.5	1	8.5	ns
t <sub>PHL</sub>					5.1	7.5	1	8.5	

**Operating Characteristics**

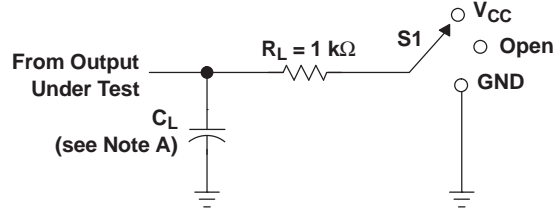
V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load, f = 1 MHz	15	pF

PARAMETER MEASUREMENT INFORMATION

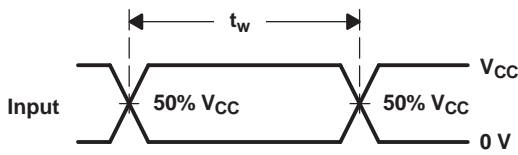


LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

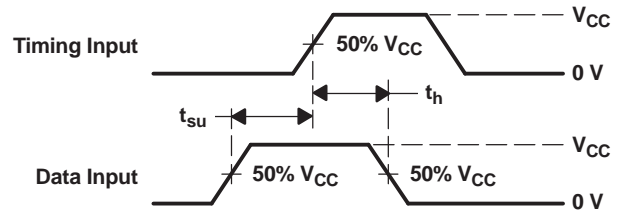


LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS

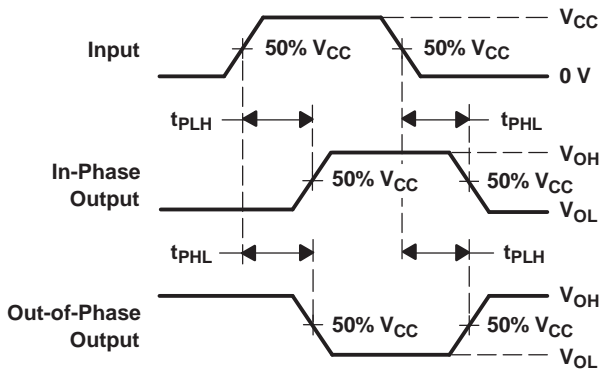
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZH}$	VCC
$t_{PHZ}/t_{PZH}$	GND
Open Drain	VCC



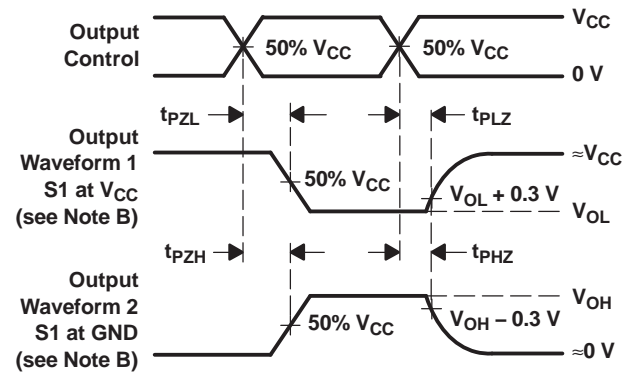
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.  
D. The outputs are measured one at a time, with one input transition per measurement.  
E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC1G02MDCKREP	SC70	DCK	5	3000	180.0	8.4	2.4	2.5	1.2	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHC1G02MDCKREP	SC70	DCK	5	3000	202.0	201.0	28.0





# EXAMPLE BOARD LAYOUT

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X



SOLDER MASK DETAILS

4214834/F 08/2024

NOTES: (continued)

- 7. Publication IPC-7351 may have alternate designs.
- 8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE: 18X

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NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

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